	·	-				
	L Number		Hits	Search Text	DB	Time stamp
	1	1	1396	wafer near ((thin or thinning or etch or	VIGD2 F	0004/04/00
	*	1 .	1390	water hear ((thin or thinning or etch or	USPAT;	2004/04/29
•	1		,	etching or grind or grinding) and (holder	US-PGPUB;	14:06
		1		or handle or temporary or support))	EPO; JPO;	
					DERWENT;	-X-
			1056		IBM_TDB	
	2 '	1 .	1056		USPAT;	2004/04/29
				etching or grind or grinding) and (holder	US-PGPUB;	14:07.
	1 4 1			or handle or temporary or support))) and	EPO; JPO;	1
	' '			(@ad<20010601)	DERWENT;	
			•		IBM TDB	
	3 .		399		USPAT;	2004/04/29
				or etching or grind or grinding) and	US-PGPUB;	12:51
				(holder or handle or temporary or	EPO; JPO;	-
			*	support))) and (@ad<20010601)) and (Wafer	DERWENT;	
				near (via or thu or through or hole or	_IBM_TDB	
				holes or vias or opening or open or gap))		
	4]	207	(((wafer near ((thin or thinning or etch	USPAT;	2004/04/29
	·			or etching or grind or grinding) and	US-PGPUB;	14:03
	-	١,		(holder or handle or temporary or.	EPO; JPO;	1 03
				support))) and (@ad<20010601)) and (Wafer	DERWENT;	h J
	· ·			near (via or thu or through or hole or		[]
*		<u>.</u> .		holes or vias or opening or open or	IBM_TDB	
		1		gap))) and (Wafer near silicon)	3	
٠,	5	-	.35	5286671.URPN.		
			33	.32000/1.ORPN.	USPAT	2004/04/29
	6		. 0	420/464 1 1		13:57
	· °		٠,٠	438/464.ccls. and beol	USPAT;	2004/04/29
			` '		US-PGPUB;	14:05
	· ·		1		EPO; JPO;	
					DERWENT;	
	·				IBM TDB	
	· 7		1	(((wafer near ((thin or thinning or etch	USPAT;	2004/04/29
	'			or etching or grind or grinding) and	US-PGPUB;	14:04
-	٠ .			(holder or handle or temporary or	EPO; JPO;	
				support))) and (@ad<20010601)) and (Wafer	DERWENT;	
				near (via or thu or through or hole or	IBM TDB	
-			: 1	holes or vias or opening or open or		
	(3)			gap))) and (beol or (back near line))		
	8	1	8646	(@ad<20010601) and (beol or (back near	USPAT;	2004/04/29
				line))	US-PGPUB;	14:04
Į			.		EPO; JPO;	1
			.		DERWENT;	
					IBM TDB	(Table)
.	9		3	((@ad<20010601) and (beol or (back near	USPAT;	2004/04/29
	• [line))) and (wafer near ((thin or	US-PGPUB;	14:05
	*		. 7	thinning or etch or etching or grind or	EPO; JPO;	13.00
				grinding) and (holder or handle or		
	· , [temporary or support)))	DERWENT;	
	10	s1	2	438/464.ccls. and (back near line)	IBM_TDB	2004/04/05
-:]	-		-	rects. and (back near time)	USPAT;	2004/04/29
					US-PGPUB;	14:06
		•	ĺ		EPO; JPO;	• •
-	,		- 1		DERWENT;	· .
4	11		46	//024<20010<01)1/0 2	IBM_TDB	
		24	40	((@ad<20010601) and (beol or (back near	USPAT;	2004/04/29
- 1		,	٠.	line))) and (wafer with (holder or handle	US-PGPUB;	14:07
	. [٠.	· · · · · · · · · · · · · · · · · · ·	or temporary or support))	EPO; JPO;	
			В		DERWENT;	
					IBM_TDB	
	12		.46	(((@ad<20010601) and (beol or (back near	USPAT;	2004/04/29
				line))) and (wafer with (holder or handle	US-PGPUB;	14:07
			· .	or temporary or support))) and	EPO; JPO;	
			1	(@ad<20010601)	DERWENT;	. 1
L					IBM TDB	
				· .		